



Laboratory Scope

Section	Equipment	Use	Standard
3.1 Thickness Testing	X-ray Fluorescence Testers	Test thickness of Tin, Tin/Lead, and Nickel plating	Reference ASTM B568
	Kocour Thickness Tester	Test thickness of Copper plating	Reference ASTM B504
3.2 Solderability Testing	Solder Pot	Determine the solderability of Tin and Tin/Lead plating	Reference ASTM B545
3.3 Steam Age Testing	Steam Vessel and Heating Unit	Determine the solderability of Tin and Tin/Lead plating	Mil. Std 202F, ANSI 002A, ASTM B579-73, Siemens Spec. 14N0345
3.4 Adhesion Testing		Use bend test, scribe/grid test, or burnishing test to determine the quality of a plating finish	ASTM B571-97
3.5 Plating Bath Analysis	Titration equipment, Hull Cell	Determine the metal and acid levels of various baths in order to maintain plating quality	Metal Finishing Guidebook, Manufacturer Specifications
3.6 Temperature Measurement	Thermometers	Monitoring the temperature of the solder pot as well as various plating baths	NIST Special Publication 819
3.7 Reflectivity	Gardner Tri-Gloss Meter	Determine the reflectivity/gloss of various finishes	Metal Finishing Guidebook
3.8 Waste Water Quality Measurement	Hach DR3000 Spectrophotometer	Determine levels of Copper and Nickel in waste water	USEPA method 8506 & 8150
3.9 Oven Testing	Blue M Lab Oven, Omxie AS-5001 Reflow Oven	Determine the effects of high temperatures on various finishes	Metal Finishing Guidebook
3.10 PH Measurement	PH Meters	Determine the pH of various plating baths to maintain plating quality	Metal Finishing Guidebook
3.11 Surface Roughness	Hommel T1000 Surface Roughness Gauge	Check surface roughness of customer base material and finished plated surfaces	ISO 4287:1997

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Selective Plating, Inc. 240 South Lombard Road Addison IL 60101 Tel 630-543-1380 Fax 630-543-1392

www.SelectivePlatingInc.com